Yeping Wang

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Education

University of Wisconsin-Madison, Madison, WI Ph.D. in Computer Sciences

Research Advisor: Prof. Michael Gleicher

Johns Hopkins University, Baltimore, MD

M.S.E. in Robotics

August 2018 - May 2020

GPA: 3.97/4.0

August 2020 - present

GPA: 3.93/4.0

Research Advisor: Prof. Chien-Ming Huang

South China University of Technology, Guangzhou, China September 2014–June 2018 B.E. in Mechanical Engineering GPA: 3.88/4.0

Publications

Peer-Reviewed Conference Papers

- 5. Wang, Y., Praveena, P., Rakita, D., Gleicher, M. (2023). RangedIK: An Optimization-Based Robot Motion Generation Method for Ranged-Goal Tasks. 2023 IEEE International Conference on Robotics and Automation (ICRA'23). Acceptance Rate 43%
- 4. Wang, Y., Sifferman C., Gleicher, M. (2023). Exploiting Task Tolerances in Mimicry-based Telemanipulation. 2023 IEEE/RSJ International Conference on Intelligent Robots and Systems (IROS'23). Acceptance Rate 43%
- Praveena, P., Wang, Y., Mutlu, B., Gleicher, M. (2023). Periscope: A Robotic Camera System to Support Remote Physical Collaboration. 2023 ACM SIGCHI Conference on Computer-Supported Cooperative Work & Social Computing (CSCW'23).
- 2. Praveena, P., Molina, L., **Wang, Y.**, Senft, E., Mutlu, B., Gleicher, M. (2022). Understanding Control Frames in Multi-Camera Robot Telemanipulation. 2022 ACM/IEEE International Conference on Human-Robot Interaction (HRI'22). Acceptance Rate 25%
- 1. Wang, Y., Ajaykumar, G., and Huang, C.-M. (2020). See What I See: Enabling User-Centric Robotic Assistance Using First-Person Demonstrations. 2020 ACM/IEEE International Conference on Human-Robot Interaction (HRI'20). Acceptance Rate 24%

Peer-Reviewed Journal Articles

- 2. Sifferman C., Wang, Y., Gupta, M. and Gleicher, M. (2023). Unlocking the Performance of Proximity Sensors by Utilizing Transient Histograms. *IEEE Robotics and Automation Letters*
- 1. Rupal, B.*, Mostafa, K.*, Wang, Y.*, and Qureshi, A.J. (2019). A Reverse CAD Approach for Estimating Geometric and Mechanical Behavior of FDM Printed Parts. *Procedia Manufacturing*, 34, 535-544. *Equal Contribution

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Experiences

Teaching Assistant August 2020–May 2021 CS559 Computer Graphics & CS400 Programming III, UW–Madison Madison, WI

Course Assistant January-May 2019 CS 482/682 Deep Learning, JHU Baltimore, MD

Research Intern May-July 2018 China National Engineering Research Center for Healthcare Devices Guangzhou, China

Summer Research Intern June-September 2016 University of Alberta Edmonton, Canada

Mentor: Prof. Ahmed Qureshi

Honors and Awards

CS Departmental Summer RA-ship, University of Wisconsin-Madison	2021
CS Departmental Scholarship, University of Wisconsin-Madison	2020
Annual 10 Merit Students, South China University of Technology	2017
China National Scholarship, Ministry of Education of the P.R. China	2016
China National Scholarship, Ministry of Education of the P.R. China	2015

Technical Skills

Programming C++, Python, Rust, JavaScript, MATLAB, HTML, CSS, LATEX

Frameworks/Libraries ROS, MoveIt!, PyTorch, OpenCV, ACADO, Git, Docker, THREE.js, D3.js

Software Adobe Illustrator, SolidWorks, ANSYS, AutoCAD, and Inventor

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